IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						ials and Mfg Information				
Supplier Inforn	nation															
Company name* Company unique				que ID [			Unique ID Authority					Response Date*				
onsemi													2025-08-21			
Contact Name			Title - Contact			]	Phone - Contact*					Email - Contact*				
Product-Env-Stews	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Authorized Representative* Ti				Title - Representative			Phone - Representative*					Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Request	juester Item Number Mfr Iter		m Number Mfr Item Name					ate \	Version	Ma	Manufacturing Site		Veight*	k	UOM	Unit Type
		74LCXR162245MTX I		LV 16-Bit Buf/Line 25Ohm			2025-08-21	5-08-21 PH4		4	191.762			mg	Each	
<b>Janufacturing</b>	<b>Proccess Informat</b>	tion														
Terminal	l Plating / Grid Array Material		Terminal Base Alloy		-STD-020 MSL Rating		Peak Process Body Tempera		rature	ture Max Time at Peak T		re Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 2		2		260		С		30 seco		ds 3			
Comments																
TTENTION: MS	L 2 Rated item requires	Dry Pack (	after electrical	test)												
or more informati	on regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.3	mg	Supplier	Silicon (Si)	7440-21-3		2.3	mg
Die Attach	0.272	mg		Bismaleimide Resin	proprietary data		0.0449	mg
			Supplier	Other Additive Agents	Proprietary Data		0.0095	mg
			Supplier	Silver (Ag)	7440-22-4		0.2176	mg
Lead Frame	70.195	mg	Supplier	Zinc (Zn)	7440-66-6		0.0842	mg
			Supplier	Iron (Fe)	7439-89-6		1.6496	mg
			Supplier	Copper (Cu)	7440-50-8		68.4401	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0211	mg
Mold Compound-Black	111.1	mg		Epoxy resin	proprietary data		11.11	mg
			Supplier	Phenol Resin	Proprietary Data		5.2217	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3333	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		94.435	mg
Plating	6.705	mg	Supplier	Palladium (Pd)	7440-05-3		0.2286	mg
			В	Nickel (Ni)	7440-02-0		6.3999	mg
			Supplier	Gold (Au)	7440-57-5		0.0764	mg
Wire Bond - Au	1.19	mg	Supplier	Gold (Au)	7440-57-5		1.19	mg